



**Surface Mount Schottky Barrier Rectifier**

**Reverse Voltage - 40 to 200 V**

**Forward Current - 2.0A**

**FEATURES**

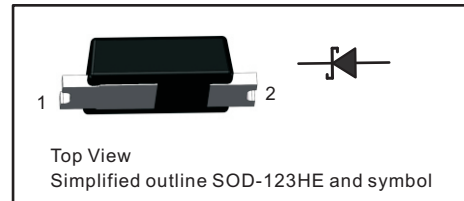
- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

**MECHANICAL DATA**

- Case: SOD-123HE
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 14mg/0.0005oz

**PINNING**

PIN	DESCRIPTION
1	Cathode
2	Anode



**Absolute Maximum Ratings and Electrical characteristics**

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	SS24HE	SS26HE	SS210HE	SS215HE	SS220HE	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	40	60	100	150	200	V
Maximum RMS voltage	$V_{RMS}$	28	42	70	105	140	V
Maximum DC Blocking Voltage	$V_{DC}$	40	60	100	150	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	2.0					A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	$I_{FSM}$	50					A
Max Instantaneous Forward Voltage at 2 A	$V_F$	0.55	0.70	0.85	0.95		V
Maximum DC Reverse Current $T_a = 25^\circ\text{C}$ at Rated DC Reverse Voltage $T_a = 100^\circ\text{C}$	$I_R$	0.5 15	0.3 10				mA
Typical Junction Capacitance <sup>(1)</sup>	$C_j$	100	80				pF
Typical Thermal Resistance <sup>(2)</sup>	$R_{\theta JA}$	110					°C/W
Operating Junction Temperature Range	$T_j$	-55 ~ +150					°C
Storage Temperature Range	$T_{stg}$	-55 ~ +150					°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 3.81 X 3.81 cm copper pad areas.



Fig.1 Forward Current Derating Curve

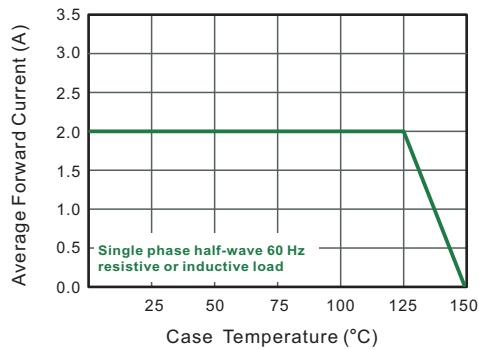


Fig.2 Typical Reverse Characteristics

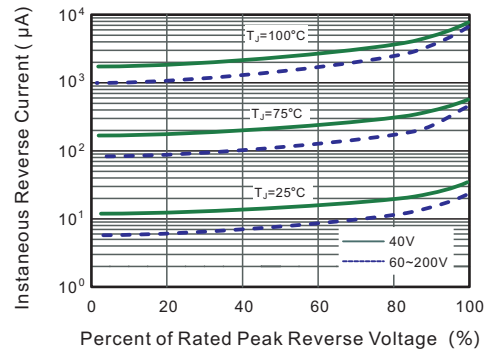


Fig.3 Typical Forward Characteristic

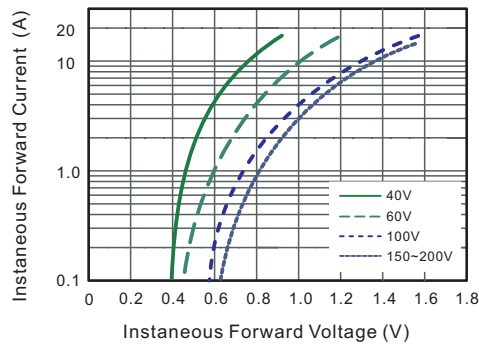


Fig.4 Typical Junction Capacitance

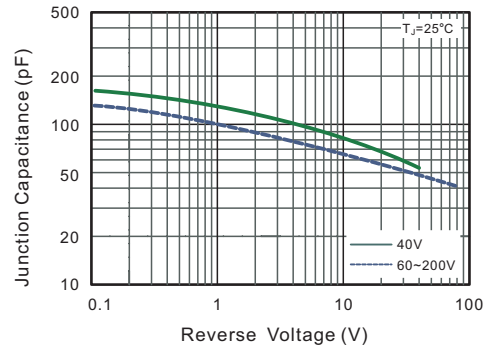


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

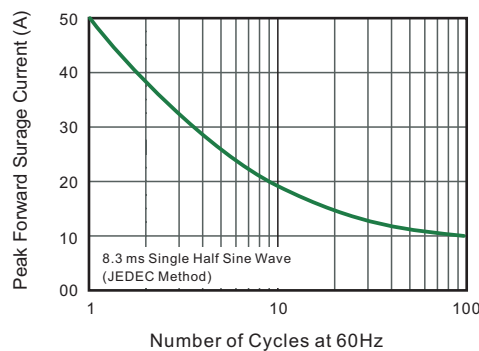
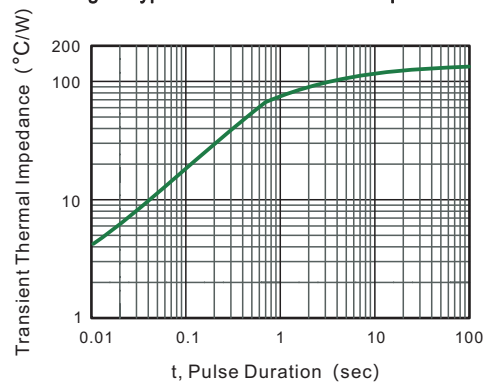


Fig.6- Typical Transient Thermal Impedance

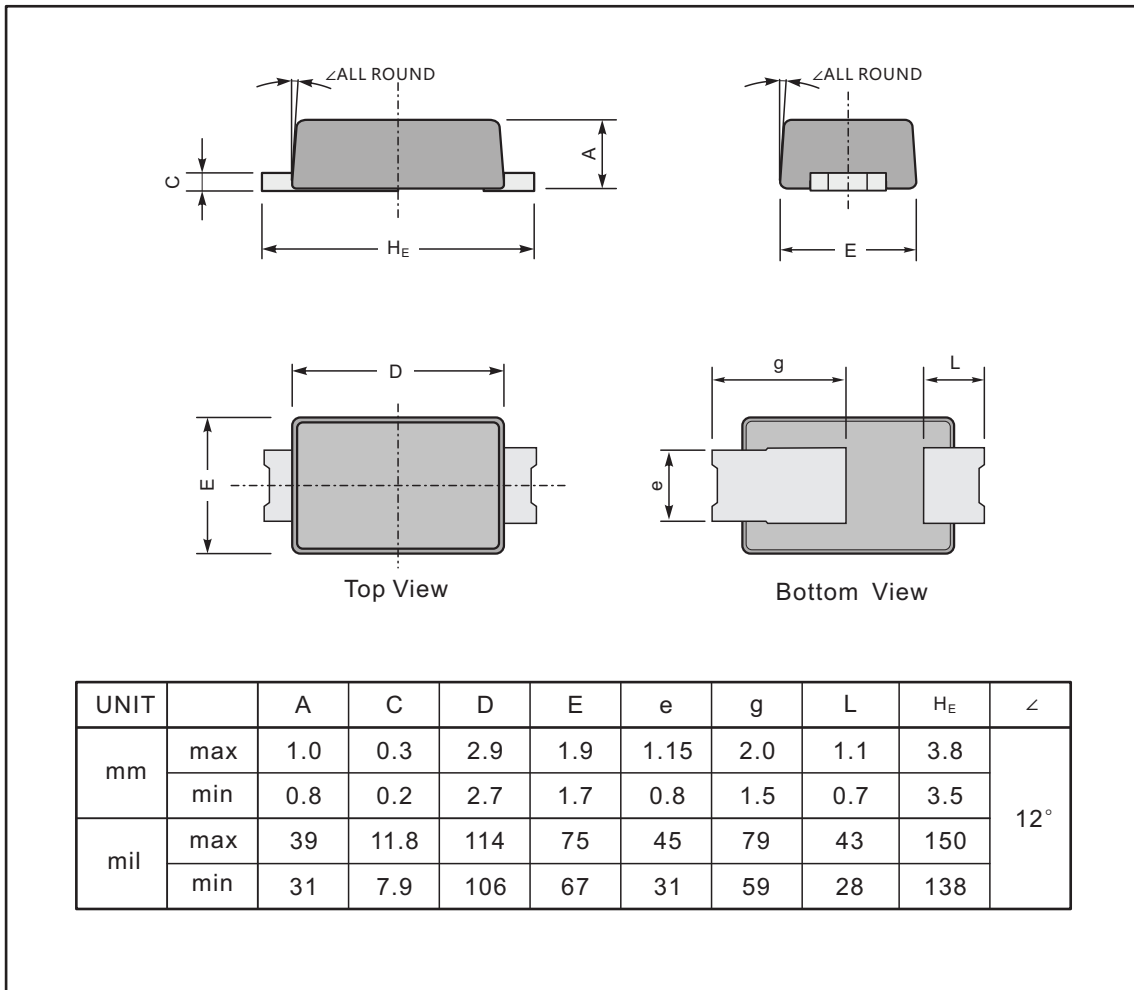




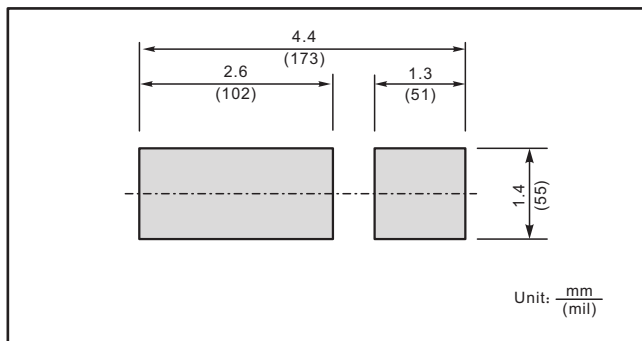
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-123HE



The recommended mounting pad size



Marking

Type number	Marking code
SS24HE	SK24
SS26HE	SK26
SS210HE	SK210
SS215HE	SK215
SS220HE	SK220



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